REMARKS

Claims 4-9, 15, and 17 are now pending in the application. Claims 4-9 and 15 are now amended. Claims 1-3, 10-14 and 16 are now cancelled. Claim 17 is now added. The claim amendments and the new claim are fully supported by the application as filed and do not present new matter. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

ELECTION/RESTRICTIONS

Claims 10, 11, and 16 stand withdrawn by the Examiner as allegedly not being sufficiently related to the other pending claims. Applicant disagrees with this restriction requirement. However, in order to expedite prosecution of this case, Applicant now cancels these claims. This election/restriction requirement is now moot.

NEW CLAIM

Independent Claim 17 is now added. All of the remaining pending claims are now amended to depend from new Claim 17.

Claim 17 recites, in part and with reference to Figures 3 and 5 for exemplary purposes only as the invention includes numerous embodiments, a first substrate 6 and a second substrate 7. The second substrate has a projected portion that projects outward further than an edge of the first substrate. A driver IC chip 80 is mounted on the projected portion of the second substrate using Chip On Glass technology. A wiring junction region 6A is provided on the projected portion of the second substrate. The wiring junction region is electrically connected to the IC chip. A first wiring board 10 is mounted to the projected portion of the second substrate and is in electrical contact with

the wiring junction region. A power IC chip 18 is mounted on the first flexible wiring board. A second flexible wiring board 30 is disposed on the first flexible wiring board at a position inboard of the first flexible wiring board. An interlayer contact portion 50 electrically connects the first flexible wiring board and the second flexible wiring board together. A surface-mounted component 44 is mounted on the second flexible wiring board.

The Tagusa et al. reference appears to disclose, with reference to Figure 3, an LCD panel 9 having a substrate 9A that opposes the substrate 9B. A portion of the substrate 9A extends beyond an edge of the substrate 9B. A flexible wiring board 41 is mounted to the portion of the substrate 9A that extends beyond the edge of the substrate 9B. A wiring board 13 is mounted to the flexible wiring board 41. The wiring board 13 is not a flexible wiring board, as admitted by the outstanding Office Action at page 3. A drive IC 1 is mounted to the flexible wiring board 41.

The Tagusa et al. reference fails to disclose or alone suggest "a driver IC chip mounted on the projected portion of the second substrate using Chip On Glass technology," as set forth in Claim 17. The drive IC 1 of the Tagusa et al. reference is mounted to the flexible board 41 and not on the projected portion of the substrate using Chip On Glass technology, as set forth in Claim 17.

The Tagusa et al. reference fails to disclose or alone suggest "a power IC chip mounted on the first flexible wiring board," as set forth in Claim 17. The Tagusa et al. reference fails to disclose or suggest a power IC chip at all.

The Tagusa et al. reference fails to disclose or alone suggest " a second flexible wiring board disposed on the first flexible wiring board at a position inboard of the first

flexible wiring board," as set forth in Claim 17. The wiring board 13 of the Tagusa et al. reference is not a flexible wiring board, as acknowledged by the Office Action at page 3.

The Tagusa et al. reference further fails to disclose or alone suggest "a surface-mounted component mounted on the second flexible wiring board," as set forth in Claim 17. The wiring board 13 of the Tagusa et al. reference has no surface-mounted components.

The Stopperan reference appears to disclose, with reference to Figure 2, a printed circuit board 20 having a first flexible dielectric substrate 42 and a second flexible dielectric substrate 52 connected to each other via a layer of conductive adhesive 74. An IC chip 70 is mounted to a dielectric cover layer 58, which is mounted to the second flexible dielectric substrate 52.

The Stopperan reference fails to disclose or alone suggest "a driver IC chip mounted on the projected portion of the second substrate using Chip On Glass technology," as set forth in Claim 17. The IC chip 70 of the Stopperan reference is mounted to dielectric cover layer 58 and not on a projected portion of the second substrate using Chip On Glass technology.

The Stopperan reference also fails to disclose or alone suggest "a power IC chip mounted on the first flexible wiring board," as set forth in Claim 17. The IC chip 70 is mounted to dielectric cover layer 58 and not on a flexible wiring board. Further, the Stopperan reference fails to disclose or suggest that the IC chip 70 is a power IC chip.

The Stopperan et al. reference fails to disclose or alone suggest "a second flexible wiring board disposed on the first flexible wiring board at a position inboard of the first flexible wiring board," as set forth in Claim 17. Elements 42 and 52 of the

Stopperan reference are not flexible wiring boards, but rather flexible dielectric substrates.

The Stopperan reference fails to disclose or alone suggest "a surface-mounted component mounted on the second flexible wiring board," as set forth in Claim 17. The IC chip 70 is mounted to cover layer 58, which is turn mounted to flexible dielectric substrate 52. The IC chip 70 is not mounted to a flexible wiring board.

As the Tagusa et al. and the Stopperan references fail to alone disclose or suggest each and every feature of Claim 17, combination of these references fails to suggest each and every feature of Claim 17. Specifically, combination of Tagusa et al. and Stopperan fails to suggest "a driver IC chip mounted on the projected portion of the second substrate using Chip On Glass technology," "a power IC chip mounted on the first flexible wiring board," "a second flexible wiring board disposed on the first flexible wiring board at a position inboard of the first flexible wiring board," and "a surface-mounted component mounted on the second flexible wiring board."

Therefore, combination of the Tagusa et al. and the Stopperan references fails to render obvious Claim 17 and those claims dependent therefrom. Applicant respectfully requests consideration and allowance of new Claim 17 because the prior art fails to disclose or suggest each and every feature of new Claim 17.

REJECTION UNDER 35 U.S.C. § 103

Claims 1-9 and 12-14 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Tagusa (U.S. Pat. No. 5,668,700) in view of Stopperan (U.S. Pat. No. 5,719,749). Claim 15 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Tagusa (U.S. Pat. No. 5,668,700) in view of Stopperan (U.S. Pat. No. 5,719,749)

and in further view of Hirakata et al. (U.S. Pat. No. 6,005,645). These rejections are respectfully traversed.

As set forth above, new Claim 17 is not disclosed or suggested by the art of record. Therefore, Claims 4-9 and 15, which are dependent upon new Claim 17, are also not obvious in light of the art of record. Claims 1-3, 10-14 and 16 are now cancelled. Therefore, this Section 103 rejection is now moot with respect to these claims.

Applicant respectfully requests reconsideration and withdrawal of this Section 103 rejection.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

Dated: May 17, 2005

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